



Typical Properties of Solid SiC

Density	Electrical Resistivity	Coefficient of Thermal Expansion (CTE)	Thermal Conductivity	Hardness (HV)	Flexural Strength	Youngs Modulus
g/cm ³	μohm-m	x 10 ⁻⁶ /°C	W / mK	Gpa	Mpa (=N/mm ²)	Gpa (=kN/mm ²)
3.21	1.0	4.0	250	26	590	450

* Non-Standard sizes may also be available upon request. Please check with your salesperson.

* Post Purification to < 5ppm and / or chemical coating on machined components is available.